

Brief Data Sheet

Issue 02

Date 2017-11-23

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Key Specifications

Processor Core

- ARM Cortex A7 @850 MHz
 - 32 KB L1 I-cache, 32 KB L1 D-cache
 - 128 KB L2 cache
 - NEON and FPU

Video Encoding/Decoding Protocols

- H.265 Main Profile, Level 4.1 decoding
- H.264 Baseline/Main/High Profile, Level 4.2 decoding
- JPEG Baseline encoding
- MJPEG/JPEG baseline decoding

Video Encoding/Decoding

- H.265/H.264/JPEG encoding and decoding of multiple streams
 - 4x1080p@20 fps H.265/H.264 decoding
 - 4x960p(1280*960)@30 fps H.265/H.264 decoding
 - 4x720p@30 fps JPEG decoding

Video and Graphics Processing

- Sharpen and contrast strengthening
- 1/15x to 16x video scaling
- 1/2x to 2x graphics scaling
- Cover regions
- OSD overlaying

Audio Encoding/Decoding

Software audio encoding and decoding complying with multiple protocols

Security Engine

 AES, DES, and 3DES algorithms implemented by hardware

Video Interfaces

- VO interfaces
 - One HDMI 1.4b output interface
 - One VGA HD output interface
 - HDMI/VGA outputs from the same source, with the maximum output of 1080p@60 fps
 - One HD video layer and 16-picture output
 - One HD PIP layer
 - One ARGB1555 or ARGB8888 HD graphics layer
 - One hardware cursor layer in ARGB1555 or ARGB8888 format (configurable) with the maximum resolution of 256 x 256

Audio Interfaces

- Two unidirectional I²S/PCM interfaces
 - One input interface, supporting dual-channel input
 - One output interface, supporting dual-channel output
 - 16-bit audio inputs and outputs
- Integrated with Audio DAC
 - $\quad 48 \text{ kHz}, 44.1 \text{ kHz}, 32 \text{ kHz sampling rates}$
 - Dual-audio channel line-out output

Ethernet Ports

• One fast Ethernet (FE) interface

- Integrated with FE PHY
- PHY, RMII, and MII modes
- 10/100 Mbit/s half-duplex or full-duplex
- TSO for reducing the CPU usage

Peripheral Interfaces

- One SATA 2.0 interface
 - PM
 - eSATA
- Two USB 2.0 host ports, supporting the hub
- Three UART interfaces, one of which supporting four wires
- One IR interface
- One I²C interface
- Multiple GPIO interfaces

Memory Interfaces

- One 16-bit DDR3/DDR3L SDRAM interface
 - Maximum frequency of 800 MHz
 - OD'
 - Maximum capacity of 512 MB
 - Automatic power consumption control
- SPI NOR/NAND flash interface
 - 1-/2-/4-wire SPI NOR/NAND flash
 - Two CSs, connected to different types of flash memories
 - Maximum capacity of 64 MB for each CS (for the SPI NOR flash)
 - Maximum capacity of 512 MB for each CS (for the SPI NAND flash)
 - 2 KB/4 KB page size (for the SPI NAND flash)
 - 8-bit/1 KB, 16-bit/1 KB, 24-bit/1 KB, or 28-bit/1 KB
 ECC (for the SPI NAND flash)
- Embedded 4 KB BOOTROM

RTC with an Independent Power Supply

• Independent battery for supplying power to the RTC

Configurable Boot Modes

- Booting from the BOOTROM
- Booting from the SPI NOR flash
- Booting from the SPI NAND flash

SDK

- Linux 4.9-based SDK
- Audio encoding and decoding libraries complying with various protocols
- High-performance H.265/H.264 PC decoding library

Physical Specifications

- Power consumption
 - Typical power consumption of 1.6 W
 - Multi-level power consumption control
- Operating voltages
 - 1.1 V core voltage
 - 1.26 V CPU voltage
 - -3.3 V I/O voltage
 - 1.5 V DDR3 SDRAM/1.35 V DDR3L SDRAM

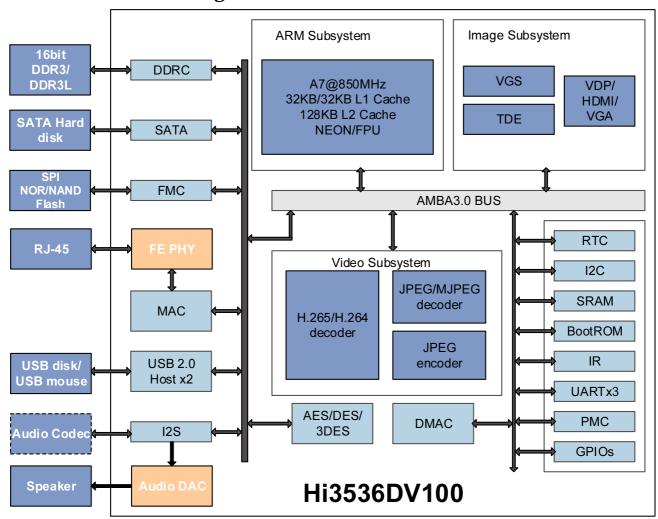


interface voltage

- Package
 - RoHS, TFBGA
 - Lead pitch of 0.65 mm (0.03 in.)

- Body size of 13 mm x 13 mm (0.51 in. x 0.51 in.)
- Operating temperature ranging from 0°C (32°F) to 70°C (158°F)

Functional Block Diagram



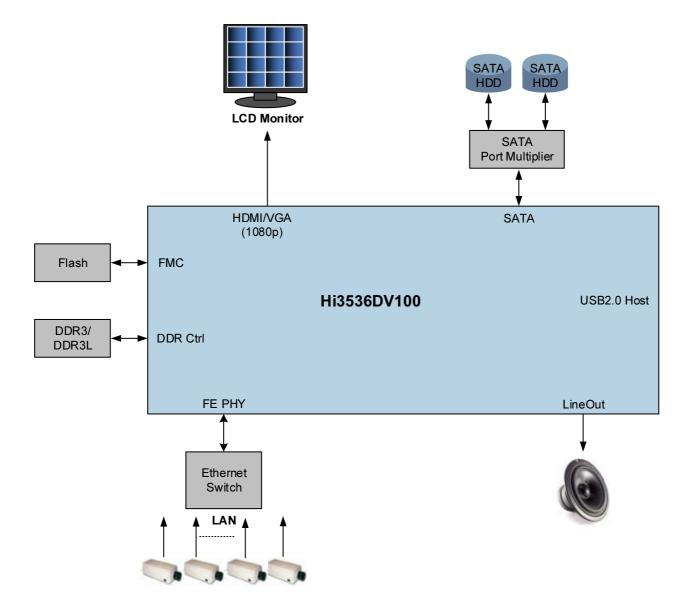
The Hi3536D V100 is a professional SoC designed for entry-level H.265 HD (4M/1080p/720p) NVRs. The Hi3536D V100 provides an embedded ARM Cortex-A7 processor, a high-performance H.265/H.264 video decoding engine, a high-performance video/graphics processing engine with various complicated graphics processing algorithms, HDMI/VGA HD outputs, and various peripheral interfaces. These features enable the Hi3536D V100 to provide high-performance, high-picture-quality, and low-cost NVR solutions for customers' products while reducing the eBOM cost.



NVRs (Each with a Hi3536D V100)

8 x 1080p NVR

- 8x IPC streams receiving (primary streams: 1080p@4 Mbit/s; secondary streams: D1@1 Mbit/s)
- 8x IPC main stream forwarding
- 2x 1080p@30 fps or 8x D1@30 fps H.265/H.264 decoding
- HDMI/VGA 1080p@60 fps outputs from the same source





Acronyms and Abbreviations

3DES triple data encryption standard

ADPCM adaptive differential pulse code modulation

AES advanced encryption standard

CBR constant bit rate
CS chip select

CVBS composite video broadcast signal DCI dynamic contrast improvement

DDR double data rate

DES data encryption standard

NVR network video recorder

eBOM engineering bill of materials

ECC error correcting code

eSATA external serial advanced technology attachment

GPIO general-purpose input/output

HD high definition

HDMI high definition multimedia interface

I²C inter-integrated circuit

I²S inter-IC sound IR infrared

MII media independent interface

ODT on-die termination
OSD on-screen display
PCM pulse code modulation
PM port multiplexer
QP quantization parameter

RMII reduced media independent interface RoHS Restriction of Hazardous Substances

ROI region of interest RTC real-time clock

SATA serial advanced technology attachment

SD standard definition
SDI serial digital interface
SDK software development kit

SDRAM synchronous dynamic random access memory

SoC system-on-chip

SPI serial peripheral interface
SRAM static random access memory
TDM time division multiplexing
TSO TCP segmentation offload

UART universal asynchronous receiver transmitter

VBR variable bit rate
VGA video graphics array
VO video output